

## REMARKS

The Examiner is respectfully requested to acknowledge the claim for the benefit of Japanese Application 2003-078354 (filed March 20, 2003) and receipt of the certified copy of the priority document.

In the Office Action mailed February 21, 2006, Figures 18-21 were objected to as not being labeled "Prior Art", claim 2 was objected to for informalities, and claims 2-11 were rejected under 35 U.S.C. 103 as being unpatentable over the Admitted Prior Art (APA) Figures 18-21 in view of Oda (JP 08-274214). The foregoing objections and rejections are respectfully traversed.

In accordance with the foregoing, Figures 18-21 and claims 2 and 8 have been amended. Claim 7 has been cancelled. Claims 2-6 and 8-11 are pending and under consideration. Claims 3-6 and 8-11 depend, either directly or indirectly, from claim 2.

Figures 18-21 are amended to be labeled "Prior Art". Withdrawal of the objections to Figures 18-21 is respectfully requested.

Claim 2 is amended to overcome the Examiner's objections to claim 2. Withdrawal of the objections to amended claim 2 is respectfully requested.

Claim 2 is further amended to recite the features of claim 7, now cancelled.

Although the Examiner asserts in the Office Action that a first substrate 153 includes a sustaining member 152 provided within an opening 157 and sustaining an exposed surface of resin, the admitted prior art discusses a capacitor 152 rather than a "sustaining member" recited in amended claim 2.

A "sustaining member" as recited in amended claim 2 is not discussed or suggested by the admitted prior art.

More particularly, amended claim 2 recites "the first substrate includes a sustaining member provided within the opening and sustaining an exposed surface of the resin". This feature of the present invention is not discussed or suggested by the admitted prior art.

Moreover, claim 2 further recites "a first electronic part inserted into the opening and bonded to the second substrate" (and claim 4 (which depends from claim 2) recites that the "first electronic part is a capacitor").

The admitted prior art does not discuss or suggest "A packaging structure for electronic parts comprising"... "a first substrate having an opening"... "a first electronic part inserted into

the opening and bonded to the second substrate"... "wherein the first substrate includes a sustaining member provided within the opening and sustaining an exposed surface of the resin", as recited in amended claim 2.

Oda does not cure the defects of the admitted prior art.

Advantageously in the present invention, a hard resin and the sustaining member sustain the weights of the second substrate, a first electronic part, and a second electronic part.

Withdrawal of the rejections of claims 2-6 and 8-11 is respectfully requested.

There being no further outstanding objections or rejections, it is submitted that the application is in condition for allowance. An early action to that effect is courteously solicited.

Finally, if there are any formal matters remaining after this response, the Examiner is requested to telephone the undersigned to attend to these matters.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

STAAS & HALSEY LLP

Date:

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By:



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**AMENDMENTS TO THE DRAWINGS:**

The attached drawing(s) include changes to FIGS. 18, 19A, 19B, 19C, 20 and 21, which label same as "PRIOR ART". The sheets containing FIGS. 18, 19A, 19B, 19C, 20 and 21 replace the original sheets.